

To: Facsimile Number: 571-273-8300

RECEIVED
CENTRAL FAX CENTER

Total Pages Sent 13

From:

Texas Instruments Incorporated
Facsimile: 972-917-4418

DEC 22 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant: Young-Joon Park, et al.

Docket Number: TI-35623

Serial No.: 10/628,198

Art Unit: 2814

Filed: 07/28/03

Examiner: Ginette Peralta

For: A Two-Step Semiconductor Manufacturing Process for
Copper Interconnects

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile
to the U.S. Patent and Trademark Office on the date shown below:

Karen Vertz
Karen Vertz

12-22-05
Date

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input checked="" type="checkbox"/> AMENDMENT 111 (12 pages)
<input type="checkbox"/> NEW APPLICATION	<input type="checkbox"/> EOT
<input type="checkbox"/> DECLARATION	<input type="checkbox"/> NOTICE OF APPEAL
<input type="checkbox"/> ASSIGNMENT	<input type="checkbox"/> APPEAL (# Pages)
<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> ISSUE FEE & PUBLICATION FEE (1 Page)
<input type="checkbox"/> INFORMAL DRAWINGS	<input type="checkbox"/> REPLY BRIEF (IN TRIPLICATE) (# Pages)
<input type="checkbox"/> CONTINUATION APP'N	
<input type="checkbox"/> DIVISIONAL APP'N	
NAME OF INVENTOR(S): Young-Joon Park, et al.	
TITLE OF INVENTION: A Two-Step Semiconductor Manufacturing Process for Copper Interconnects	
TI FILE NO.: TI-35623	DEPOSIT ACCT. NO.: 20-0668
FAXED: 12-22-05 DUE: 1-5-06 ATTY/SEC'Y: RAK/kjv	
RECEIPT DATE & SERIAL NO.: Serial No.: 10/628,198 Filing Date: 07/28/03	

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265-5474

RECEIVED
CENTRAL FAX CENTER

DEC 22 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Park et al.

Docket No.: TI-35623

Serial No.: 10/628,198

Art Unit: 2814

Filed: 07/28/2003

Examiner: Peralta, Ginette

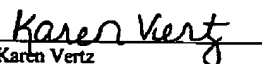
Title: A Two-Step Semiconductor Manufacturing Process for Copper Interconnects

AMENDMENT UNDER 37 C.F.R. §1.111

December 22, 2005

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Commissioner:

CERTIFICATION OF FACSIMILE TRANSMISSION	
I hereby certify that the above correspondence is being transmitted by facsimile to the U.S. Patent and Trademark Office at 571-273-8300 on the date shown below.	
 Karen Vertz	<u>12-22-05</u> Date

In response to the Office Action, dated 10/05/2005, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Please charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.